ABSTRACT

A substrate processing apparatus (2) includes a substrate holder (11) configured to hold and rotate a substrate (W), an inert-gas nozzle (14) oriented toward an inside of the substrate holder (11), an inert-gas supply line (41) coupled to the inert-gas nozzle (14) and configured to supply an inert gas to the inert-gas nozzle (14), an inert-gas saturated water nozzle (15) oriented toward the inside of the substrate holder (11), and an inert-gas saturated water supply line (48) coupled to the inert-gas saturated water nozzle (15) and configured to supply an inert-gas saturated water in which an inert gas is saturated to the inert-gas saturated water nozzle (15).

Figure 2